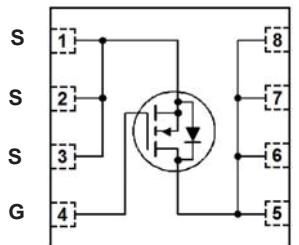


N-Channel MOSFET

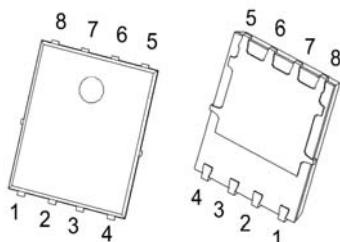
2KK6015DFN

■ Features

- V_{DS} (V) = 150 V
- I_D = 70 A
- $R_{DS(ON)}$ = 13 mΩ (typ.) @ V_{GS} = 10 V



DFN5x6-8(PDFNWB5x6-8L)

■ Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current $T_C = 25^\circ C$	I_D	70	A
		49.5	
Pulsed Drain Current	I_{DM}	280	mJ
Single Pulse Avalanche Energy (Note 1)	E_{AS}	583	
Power Dissipation	P_D	150	W
Thermal Resistance, Junction- to-Case (Note 2)	$R_{\theta JC}$	0.83	
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{Stg}	-55 to 150	

Notes:

1. EAS condition : $T_J=25^\circ C$, $V_{DD}=50V$, $V_G=10V$, $L=0.5mH$, $R_g=25\Omega$
2. Surface Mounted on FR4 Board, $t \leq 10$ sec. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$. the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

N-Channel MOSFET

2KK6015DFN

■ Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

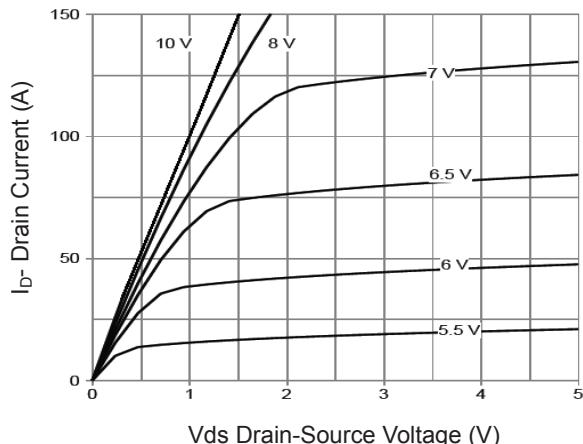
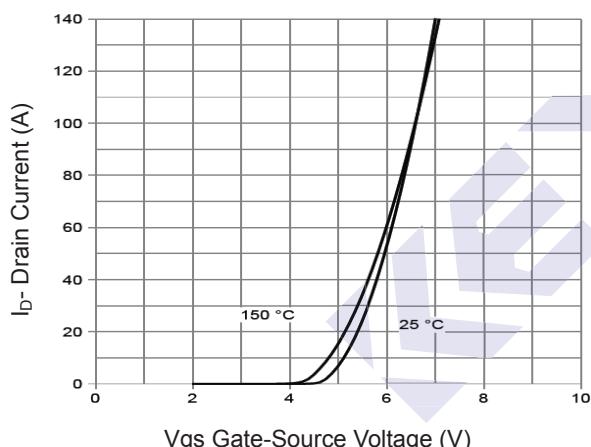
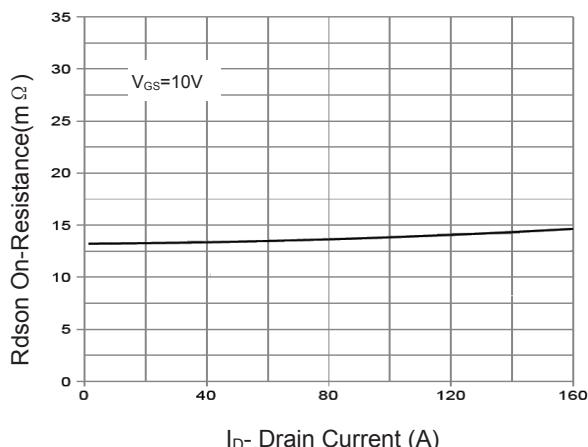
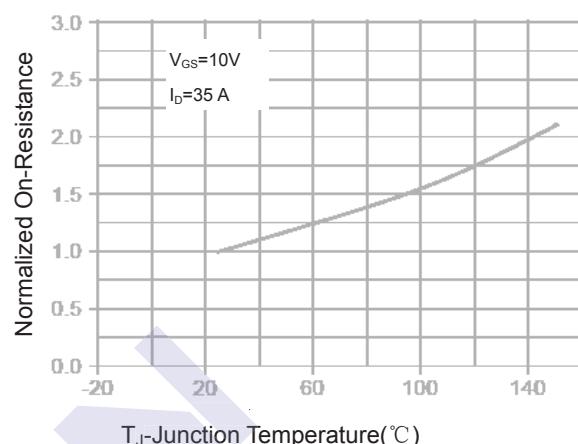
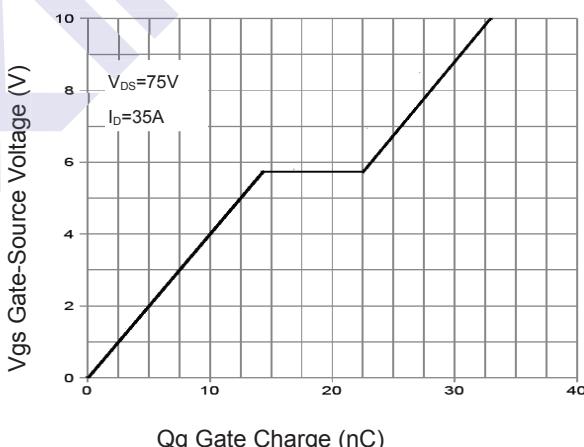
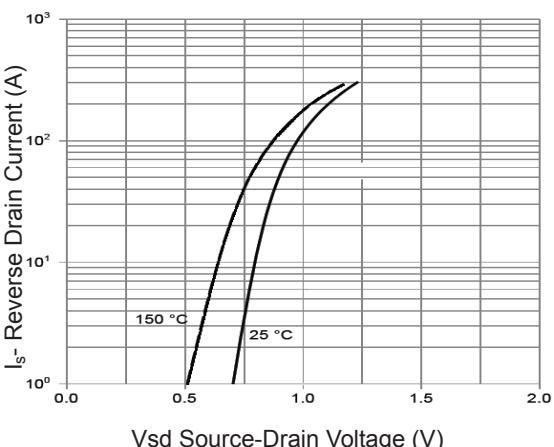
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{I}_D = 250 \mu\text{A}, \text{V}_{\text{GS}} = 0\text{V}$	150			V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}} = 150\text{ V}, \text{V}_{\text{GS}} = 0\text{ V}$			1	μA
Gate to Source Leakage Current	I_{GSS}	$\text{V}_{\text{DS}} = 0\text{ V}, \text{V}_{\text{GS}} = \pm 20\text{ V}$			± 100	nA
On Characteristics (Note 3)						
Gate to Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$	2.0		4.0	V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10\text{ V}, \text{I}_D = 35\text{ A}$		13	15	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$\text{V}_{\text{DS}} = 5\text{ V}, \text{I}_D = 35\text{ A}$		58		S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$\text{V}_{\text{GS}} = 0\text{ V}, \text{V}_{\text{DS}} = 75\text{ V}, \text{f} = 1\text{ MHz}$		2200		pF
Output Capacitance	C_{oss}			289		
Reverse Transfer Capacitance	C_{rss}			11.2		
Switching Characteristics (Note 4)						
Total Gate Charge	Q_g	$\text{V}_{\text{GS}} = 10\text{V}, \text{V}_{\text{DS}} = 75\text{ V}, \text{I}_D = 35\text{ A}$		33		nC
Gate Source Charge	Q_{gs}			14.5		
Gate Drain Charge	Q_{gd}			8		
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{GS}} = 10\text{V}, \text{V}_{\text{DD}} = 75\text{ V}, \text{I}_D = 35\text{A}, \text{R}_G = 3\Omega$		12.5		ns
Turn-On Rise Time	t_r			3.8		
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$			14		
Turn-Off Fall Time	t_f			3.5		
Drain-Source Diode Characteristics						
Body Diode Reverse Recovery Time	t_{rr}	$\text{I}_F = 35\text{A}, \text{di/dt} = 100\text{ A}/\mu\text{s}$		47		ns
Body Diode Reverse Recovery Charge	Q_{rr}			55		nC
Maximum Body-Diode Continuous Current	I_{s}				70	A
Diode Forward Voltage (Note 3)	V_{SD}	$\text{V}_{\text{GS}} = 0\text{ V}, \text{I}_{\text{s}} = 35\text{ A}$			1.2	V

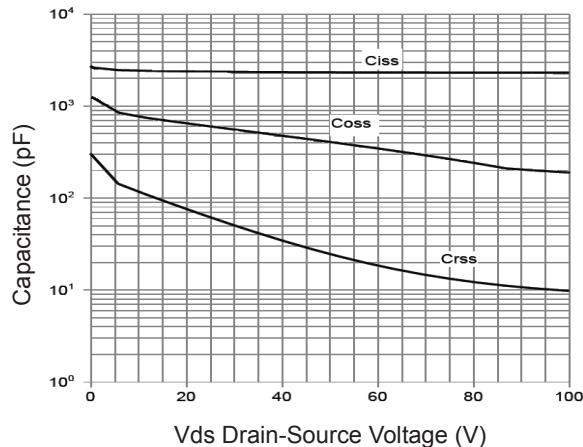
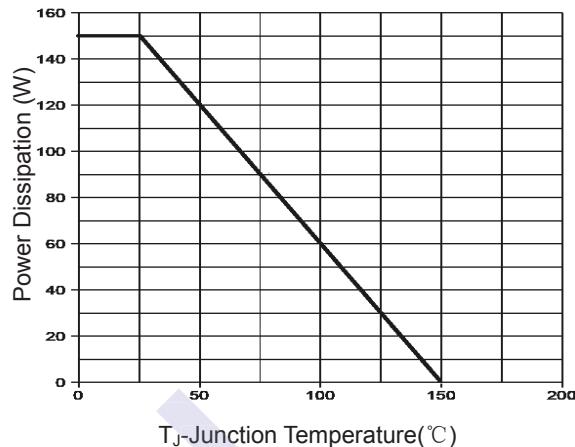
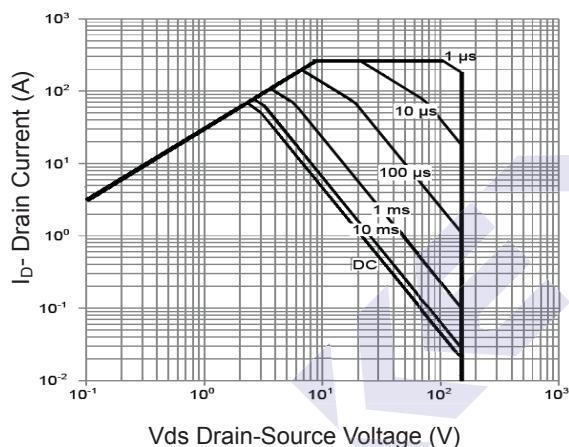
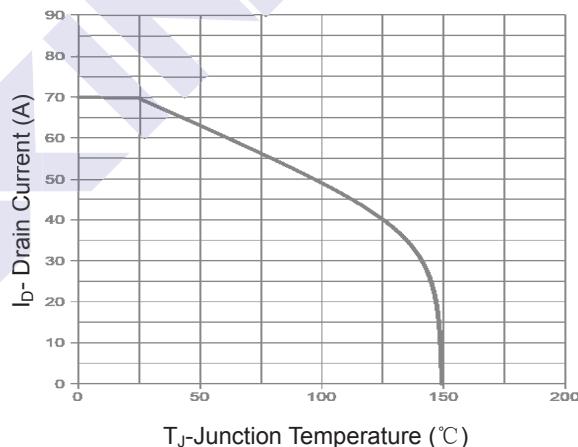
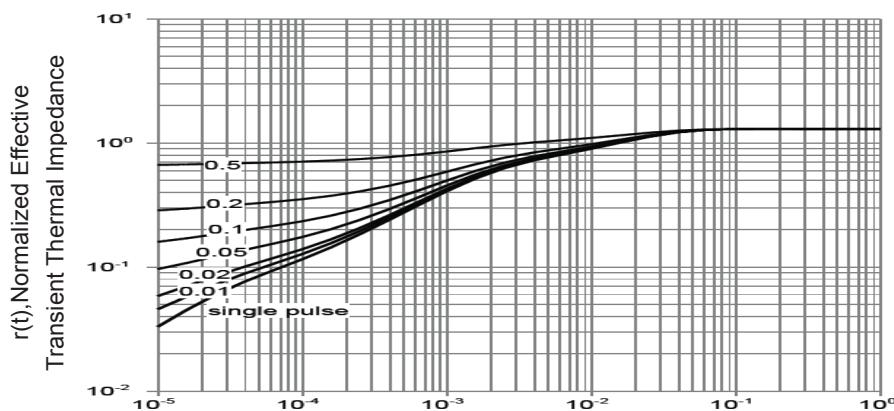
Notes:

3. Pulse Test: Pulse Width $\leqslant 300\text{ }\mu\text{s}$, Duty Cycle $\leqslant 2\%$.
4. Guaranteed by design, not subject to production.

■ Marking

Marking	K6015 KC***
---------	----------------

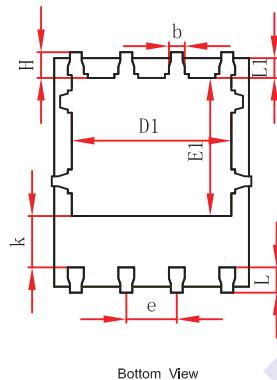
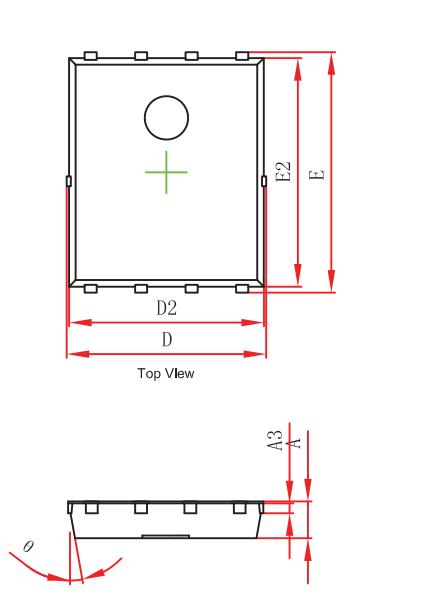
N-Channel MOSFET**2KK6015DFN****■ Typical Characteristics****Figure 1 Output Characteristics****Figure 2 Transfer Characteristics****Figure 3 Rdson- Drain Current****Figure 4 Rdson-Junction Temperature****Figure 5 Gate Charge****Figure 6 Source- Drain Diode Forward**

N-Channel MOSFET**2KK6015DFN****Figure 7 Capacitance vs Vds****Figure 9 Power De-rating****Figure 8 Safe Operation Area****Figure 10 Current De-rating****Figure 11 Normalized Maximum Transient Thermal Impedance**

N-Channel MOSFET

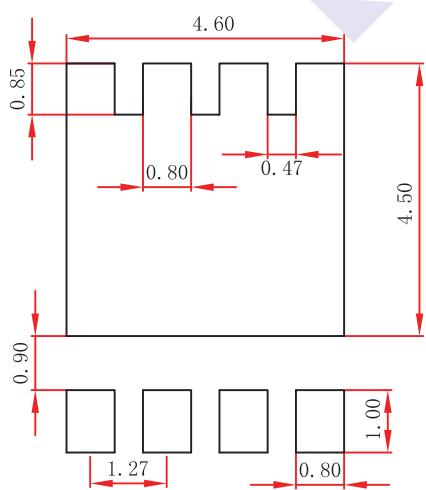
2KK6015DFN

■ DFN5x6-8(PDFNWB5x6-8L) Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

■ DFN5x6-8(PDFNWB5x6-8L) Suggested Pad Layout



Note:

1. Controlling dimension:in millimeters.
- 2.General tolerance: $\pm 0.05\text{mm}$.
- 3.The pad layout is for reference purposes only.